



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	21-08-2017
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	MDG MD CHAMPION	<b>Representative Title</b>	MDG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F302VBT6 STM32F302VBT6TR	941L*422XXXY	B	959	21-08-2017
Amount	UoM	Unit type	ST ECOPACK Grade	
681,44	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Matte Tin(Sn)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	100	L bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	941L*422XXX				6000000.0	0.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	18,560	mg	supplier	die	Silicon (Si)	7440-21-3		17,666	mg	951832	25925
				supplier	metallization	Aluminium (Al)	7429-90-5		0,051	mg	2748	75
				supplier	metallization	Copper (Cu)	7440-50-8		0,255	mg	13739	374
				supplier	metallization	Cobalt (Co)	7440-48-4		0,048	mg	2586	70
				supplier	metallization	Titanium (Ti)	7440-32-6		0,014	mg	754	21
				supplier	metallization	Tungsten (W)	7440-33-7		0,028	mg	1509	41
				supplier	Passivation	Silicon Nitride	12033-89-5		0,033	mg	1778	48
				supplier	Passivation	Silicon Oxide	7631-86-9		0,323	mg	17403	474
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0,142	mg	7651	208
				LEADFRAME	M-011 Other inorganic materials	156,345	mg	supplier	ALLOY	Copper (Cu)	7440-50-8	
supplier	ALLOY	Iron (Fe)	7439-89-6						3,621	mg	23160	5314
supplier	ALLOY	Iron Phosphide (Fe2P)	1310-43-6						0,045	mg	288	66
supplier	ALLOY	Zinc (Zn)	7440-66-6						0,181	mg	1158	266
supplier	SPOT	Silver (Ag)	7440-22-4						5,490	mg	35112	8056
DIE ATTACH	M-011 Other inorganic materials	2,904	mg	supplier	GLUE	Silver (Ag)	7440-22-4		2,483	mg	855000	3644
				supplier	GLUE	Dodecyl acrylate	2156-97-0		0,073	mg	25000	107
				supplier	GLUE	methylene diacrylate	42594-17-2		0,232	mg	80000	341
				supplier	GLUE	Diglycidylphenyl glycidyl ether	13561-08-5		0,058	mg	20000	85
				supplier	GLUE	Isobornyl Methacrylate	7534-94-3		0,029	mg	10000	43
				supplier	GLUE	dimethylbenzyl peroxide	80-43-3		0,029	mg	10000	43
BONDING WIRE	M-011 Other inorganic materials	1,534	mg	supplier	BONDING WIRE	Silver (Ag)	7440-22-4		1,480	mg	965000	2172
				supplier	BONDING WIRE	Gold (Au)	7440-57-5		0,008	mg	5000	11
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0,046	mg	30000	68
ENCAPSULATION	M-011 Other inorganic materials	496,640	mg	supplier	MOLDING COMPOUND	Silica, vitreous	60676-86-0		429,260	mg	864366	-370070
				supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		37,158	mg	74798	54529
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		24,772	mg	49865	36353
				supplier	MOLDING COMPOUND	3-Mercaptopropyl trimethoxysilane	4420-74-0		2,477	mg	4987	3635
				supplier	MOLDING COMPOUND	Quartz	14808-60-7		1,486	mg	2992	2181
FINISHING	M-011 Other inorganic materials	5,457	mg	supplier	MOLDING COMPOUND	Carbon black	1333-86-4		1,486	mg	2992	2181
				supplier	COATING	Tin (Sn)	7440-31-5		5,457	mg	1000000	8008